

## **AMENDMENTS TO THE SPECIFICATION**

Please amend Paragraphs [0002], [0010] and [0018] of the specification as follows:

[0002] This application is also related to the following applications and patents: (a) Application Serial No. 10/329,023 (Publication No. 2003/0112491, now U.S. Patent No. 6,727,881), filed December 24, 2002; (b) Application Serial No. 09/140,846, filed August 27, 1998, of which the aforementioned Application Serial No. 10/329,023 is a continuation; (c) Application Serial No. 08/504,896, filed July 20, 1995 (now U.S. Patent No. 6,124,851), of which the aforementioned Application Serial No. 09/140,846 is a continuation-in-part; (d) Application Serial No. 08/983,404, filed March 26, 1999, of which the aforementioned Application Serial No. 09/140,846 is a continuation-in-part; (e) International Application No. PCT/US96/12000 (Publication No. WO 97/04398), of which the aforementioned Application Serial No. 08/983,404 is the United States national phase; (f) Application Serial No. 08/935,800, filed September 23, 1997 (now U.S. Patent No. 6,120,588), of which the aforementioned Application Serial No. 09/140,846 is a continuation-in-part; (g) Provisional Applications Serial Nos. 60/057,118; 60/057,122; 60/057,133; 60/057,163; 60/057,716; 60/057,798; 60/057,799; 60/059,358; 60/059,543; 60/065,529; 60/065,605; 60/065,630; 60/066,115; 60/066,147; 60/066,245; 60/066,246; 60/066,334; 60/066,418; 60/070,935; 60/070,939; 60/070,940; 60/071,371; 60/072,390; 60/074,454; 60/076,955; 60/076,956; 60/076,957; 60/076,959; 60/076,978; 60/078,363; 60/081,362; 60/081,374; 60/083,252; 60/085,096; 60/090,222; 60/090,223; 60/090,232; 60/092,046; 60/092,050; 60/092,742; and 60/093,689; from all of which the aforementioned Application Serial No. 09/140,846 claims priority; (h) Application Serial No. 10/064,279, filed June 28, 2002 (now U.S. Patent No. 6,657,772); (i) Application Serial No. 60/304,015, filed July 9, 2001, from which the aforementioned Application Serial No. 10/064,279 claims priority; (j) Application Serial No. ~~[[10/249,975]]~~10/249,957, filed May 23, 2003 (Publication No. 2004/0027327); (k) Application Serial No. 10/605,024, filed September 2, 2003 (Publication No.

2004/0155857); and (l) U.S. Patent 6,312,304. The entire contents of all the aforementioned applications, and of all United States Patents, published applications and copending applications mentioned below are herein incorporated by reference.

[0010] Numerous patents and applications assigned to or in the names of the Massachusetts Institute of Technology (MIT) and E Ink Corporation have recently been published describing encapsulated electrophoretic media. Such encapsulated media comprise numerous small capsules, each of which itself comprises an internal phase containing electrophoretically-mobile particles suspended in a liquid suspension medium, and a capsule wall surrounding the internal phase. Typically, the capsules are themselves held within a polymeric binder to form a coherent layer positioned between two electrodes. Encapsulated media of this type are described, for example, in U.S. Patents Nos. D485,294; 5,930,026; 5,961,804; 6,017,584; 6,067,185; 6,118,426; 6,120,588; 6,120,839; 6,124,851; 6,130,773; 6,130,774; 6,172,798; 6,177,921; 6,232,950; [[6,249,721]]6,249,271; 6,252,564; 6,262,706; 6,262,833; 6,300,932; 6,312,304; 6,312,971; 6,323,989; 6,327,072; 6,376,828; 6,377,387; 6,392,785; 6,392,786; 6,413,790; 6,422,687; 6,445,374; 6,445,489; 6,459,418; 6,473,072; 6,480,182; 6,498,114; 6,504,524; 6,506,438; 6,512,354; 6,515,649; 6,518,949; 6,521,489; 6,531,997; 6,535,197; 6,538,801; 6,545,291; 6,580,545; 6,639,578; 6,652,075; 6,657,772; 6,664,944; 6,680,725; and 6,683,333; and U.S. Patent Applications Publication Nos. 2002/0019081; 2002/0021270; 2002/0053900; 2002/0060321; 2002/0063661; 2002/0063677; 2002/0090980; 2002/0106847; 2002/0113770; 2002/0130832; 2002/0131147; 2002/0145792; 2002/0171910; 2002/0180687; 2002/0180688; 2002/0185378; 2003/0011560; 2003/0011868; 2003/0020844; 2003/0025855; 2003/0034949; 2003/0038755; 2003/0053189; 2003/0076573; 2003/0096113; 2003/0102858; 2003/0132908; 2003/0137521; 2003/0137717; 2003/0151702; 2003/0189749; 2003/0214695; 2003/0214697 and 2003/0222315; and International Applications Publication Nos. WO 99/67678; WO 00/05704; WO 00/38000; WO 00/38001; WO 00/36560; WO 00/67110; WO 00/67327; WO 01/07961; WO 01/08241; and WO 03/104884.

[0018] In the processes described above, the lamination of the substrate carrying the electro-optic layer to the backplane may advantageously be carried out by vacuum lamination. Vacuum lamination is effective in expelling air from between the two materials being laminated, thus avoiding unwanted air bubbles in the final display; such air bubbles may introduce undesirable artifacts in the images produced on the display. However, vacuum lamination of the two parts of an electro-optic display in this manner imposes stringent requirements upon the lamination adhesive used, especially in the case of a display using an encapsulated electrophoretic medium. The lamination adhesive must have sufficient adhesive strength to bind the electro-optic layer to the layer (typically an electrode layer) to which it is to be laminated, and in the case of an encapsulated electrophoretic medium, the adhesive must also have sufficient adhesive strength to mechanically hold the capsules together. If the electro-optic display is to be of a flexible type (and one of the important advantages of rotating bichromal member and encapsulated electrophoretic displays is that they can be made flexible), the adhesive must have sufficient flexibility not to introduce defects into the display when the display is flexed. The lamination adhesive must have adequate flow properties at the lamination temperature to ensure high quality lamination, and in this regard, the demands of laminating encapsulated electrophoretic and some other types of electro-optic media are unusually difficult; the lamination has to be conducted at a temperature of not more than about 110°C since the medium cannot be exposed to substantially higher temperatures without damage, but the flow of the adhesive must cope with the relatively uneven surface of the capsule-containing layer, the surface of which is rendered irregular by the underlying capsules. The lamination temperature should indeed be kept as low as possible, and room temperature lamination would be ideal, but no commercial adhesive has been found which permits such room temperature lamination. The lamination adhesive must be chemically compatible with all the other materials in the display. Solvent-based lamination adhesives should be avoided; it has been found (although this does not appear to have been described in the literature), that any solvent left behind in

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the adhesive after lamination has a strong tendency to introduce undesirable contaminants into the electro-optic medium.